

AMENDMENTS TO THE CLAIMS

1. **(Previously presented)** A chemically amplified positive photosensitive thermosetting resin composition comprising:

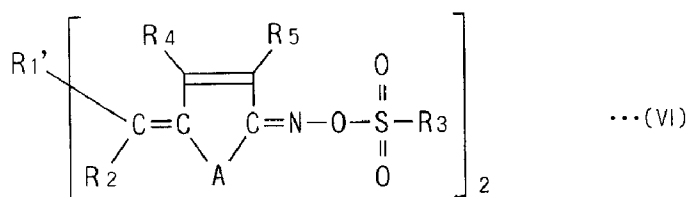
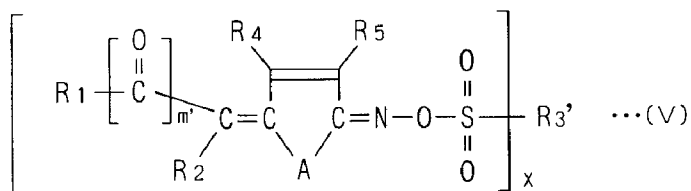
a reaction product of (A) an alkali soluble resin having a phenolic hydroxyl group and (C) a crosslinking polyvinyl ether compound;

(B) a compound generating an acid under irradiation with radiation; and

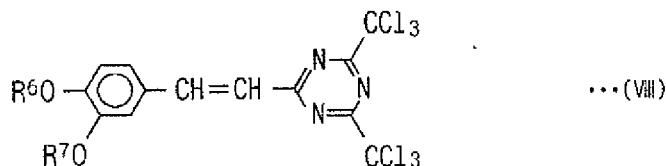
(D) an epoxy resin.

2. **(Currently amended)** A chemically amplified positive photosensitive thermosetting resin composition comprising (A) an alkali soluble resin, (B) a compound generating an acid under irradiation with radiation, (C) a crosslinking polyvinyl ether compound, and (D) an epoxy resin,

wherein (B) represented by the following general formulas (V), (VI), (VIII) or (X):



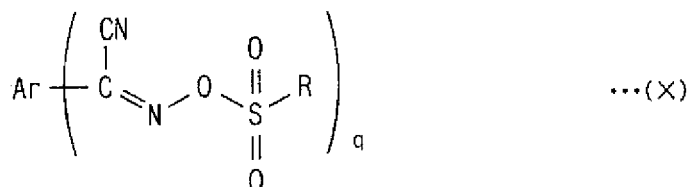
[wherein m' represents 0 or 1; X represents 1 or 2; R_1 is a phenyl group which may be substituted with one or more C_1 - C_{12} alkyl groups, or a heteroaryl group, or, when m' is 0, R_1 may further be a C_2 - C_6 alkoxy carbonyl group, a phenoxy carbonyl group or CN; R_1' represents a C_2 - C_{12} alkylene group; R_2 has the same meaning as in R_1 ; R_3 represents a C_1 - C_{18} alkyl group; R_3' has the same meaning as in R_3 when $X = 1$, or a C_2 - C_{12} alkylene group or a phenylene group when $X = 2$; R_4 and R_5 each independently represents a hydrogen atom, a halogen, or a C_1 - C_6 alkyl group; A represents S, O or NR_6 ; and R_6 represents a hydrogen atom or a phenyl group].



[wherein R⁶ and R⁷ each represents an alkyl group having 1 to 3 carbon atoms, or a combination of the compound (VIII) and a bis(trichloromethyl)triazine compound represented by the following formula (IX):



wherein Z represents a 4-alkoxyphenyl group],



[wherein Ar represents a substituted or unsubstituted phenyl group or a naphthyl group; R represents a C₁ to C₉ alkyl group; and q represents an integer of 2 or 3].

3. **(Original)** The chemically amplified positive photosensitive thermosetting resin composition according to claim 1, which comprises a curing accelerator for the component (D).
4. **(Original)** The chemically amplified positive photosensitive thermosetting resin composition according to claim 3, wherein the curing accelerator is a basic compound.
5. **(Original)** The chemically amplified positive photosensitive thermosetting resin composition according to claim 2, which comprises a curing accelerator for the component (D).
6. **(Original)** The chemically amplified positive photosensitive thermosetting resin composition according to claim 5, wherein the curing accelerator is a basic compound.

7. **(Original)** A method for formation of a cured article, which comprises applying the chemically amplified positive photosensitive thermosetting resin composition of any one of claims 1 to 6, subjecting to prebaking, subjecting to selective exposure, subjecting to PEB (post-exposure baking) and subjecting to alkali development to form a resist pattern, followed by melting with heating and further heat curing.

8. **(Original)** A cured article obtainable by the method of claim 7.

9. **(Original)** A method for production of a functional device, which comprises forming a resist pattern of and curing the chemically amplified positive photosensitive thermosetting resin composition of any one of claims 1 to 6.

10. **(Original)** A functional device obtainable by the method of claim 9.